

LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED  
INDUCTANCE AND ITS MANUFACTURING METHOD

ABSTRACT OF THE INVENTION

[0036] A semiconductor die comprising a heat sink having opposed top and bottom surfaces and defining a peripheral edge. Attached to the top surface of the heat sink is a semiconductor die. Extending at least partially about the semiconductor die is a plurality of leads, at least some of which are electrically connected to the semiconductor die. Attached to the top surface of the heat sink between the semiconductor die and the peripheral edge thereof is at least one first ground lead. Also attached to the top surface of the heat sink and protruding beyond the peripheral edge thereof is at least one second ground lead. A plurality of ground wires conductively connect the semiconductor die, the first and second ground leads and the heat sink to each other. A package body at least partially encapsulates the heat sink, the semiconductor die, the leads, the first and second ground leads, and the ground wires such that at least portions of the second ground leads and the leads protrude from the package body.